

AN-1557 LM5022 Evaluation Board

The AN-1557 is an evaluation module that demonstrates a typical 20W Boost converter featuring the LM5022 60V low-side controller in a design that shows high efficiency in a single-ended application.

Contents

1	Specifications Of The Board	2
2	Example Circuit	2
3	Powering The Converter	2
4	Loading The Converter	2
5	Enabling The Converter	2
6	Testing The Converter	
7	MOSFET Footprints	3
8	Permanent Components	4
9	Additional Footprints	4
10	Typical Performance Characteristics	6
11	Bill of Materials	
12	PC Board Layout	9

List of Figures

1	Efficiency	2
2	SO-8 MOSFET Pinout	3
3	Circuit Schematic	4
4	Efficiency Measurement Setup	4
5	Output Voltage Ripple Measurement Setup	5
6	Switch Node Voltage ($V_{IN} = 9V$, $I_{O} = 0.5A$)	6
7	Switch Node Voltage ($V_{IN} = 16V$, $I_{O} = 0.5A$)	6
8	Output Voltage Ripple AC Coupled (V _{IN} = 9V, $I_0 = 0.5A$)	6
9	Output Voltage Ripple AC Coupled (V _{IN} = 16V, $I_0 = 0.5A$)	6
10	Load Transient Response (V _{IN} = 9V, I _o = 50 mA to 0.5A)	6
11	Load Transient Response (V _{IN} = 16V, I _o = 50 mA to 0.5A)	6
12	Start Up ($V_{IN} = 9V$, $I_{O} = 0.5A$)	
13	Shut Down ($V_{IN} = 9V$, $I_{O} = 0.5A$)	
14	Start Up (V _{IN} = 16V, $I_0 = 0.5A$)	
15	Shutdown (V _{IN} = 16V, $I_0 = 0.5A$)	7
16	NGATE Rise Time (V _{IN} = 9V, I _o = 0.1A, Si4850DY)	7
17	NGATE Fall Time (V _{IN} = 12V, I_0 = 0.1A, Si4850DY)	7
18	Top Layer and Top Overlay	
19	Bottom Layer	9

All trademarks are the property of their respective owners.

1 Specifications Of The Board

The Evaluation Board has been designed for testing of various circuits using the LM5022 boost regulator controller. A complete schematic for all the components is shown in Figure 3. The board is two layers with components and power paths in 1oz. copper. The board is 62mil FR4 laminate, and a complete bill of materials is listed at the end of this document.

2 Example Circuit

The example circuit which comes on the evaluation board delivers a 40V \pm 2% output voltage at currents up to 500 mA and switches at 500 kHz. The input voltage range is optimized between 9.0V and 16.0V. The measured efficiency of the converter is 95% at an input voltage of 16V and an output current of 0.5A.

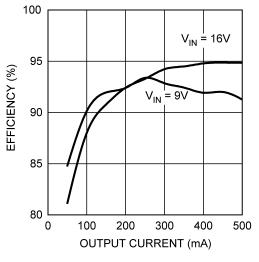


Figure 1. Efficiency

3 Powering The Converter

The example circuit for the LM5022 Evaluation Board is optimized to run at 12V, however the circuit will operate with input voltages ranging from 6.0V to 32.0V connected between the **VIN** and **GND** terminals on the right side of the board.

4 Loading The Converter

The example circuit will startup with no load at the output, and can also start up with loads of up to 0.5A as long as the input voltage is above 9.0V. The maximum output current will be reduced for input voltages below 9.0V. Fixed loads, resistors, and variable electronic loads can be connected between the **Vo** and **GND** terminals on the left side of the board.

5 Enabling The Converter

The **OFF** terminal controls the state of the converter while power is applied to the input terminals. The LM5022 is disabled whenever the voltage at **OFF** is a logic high. (Above 2.0V.) The LM5022 is enabled whenever the **OFF** terminal is open-circuited or connected to ground, in which case startup will begin as soon as the input voltages exceeds 6.0V. Upon enabling the LM5022 will perform a soft-start, after which the output is ready to supply current to the load.



6 Testing The Converter

Figure 4 shows a block diagram of connections for making measurements of efficiency. The wires used for making connections at both the input and output should be rated to at least 10A of continuous current and should be no longer than is needed for convenient testing. A series ammeter capable of measuring 10A or more should be used for both the input and the output lines. Dedicated voltmeters should be connected with their positive and negative leads right at the four power terminals at the sides of the evaluation board. This measurement technique minimizes the resistive loss in the wires that connect the evaluation board to the input power supply and the electronic load.

Output voltage ripple measurements should be taken directly across the 100 nF ceramic capacitor **Cox**, placed right between the output terminals. Care must be taken to minimize the loop area between the oscilloscope probe tip and the ground lead. One method to minimize this loop is to remove the probe's spring tip and 'pigtail' ground lead and then wind bare wire around the probe shaft. The bare wire should contact the ground of the probe, and the end of the wire can then contact the ground side of **Cox**. Figure 5 shows a diagram of this method.

7 MOSFET Footprints

The LM5022 evaluation board has a footprint for a single MOSFET with an SO-8 package using the industry standard pinout. (See Figure 2) This footprint can also accept newer MOSFET packages that are compatible with SO-8 footprints.

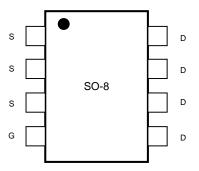


Figure 2. SO-8 MOSFET Pinout

З

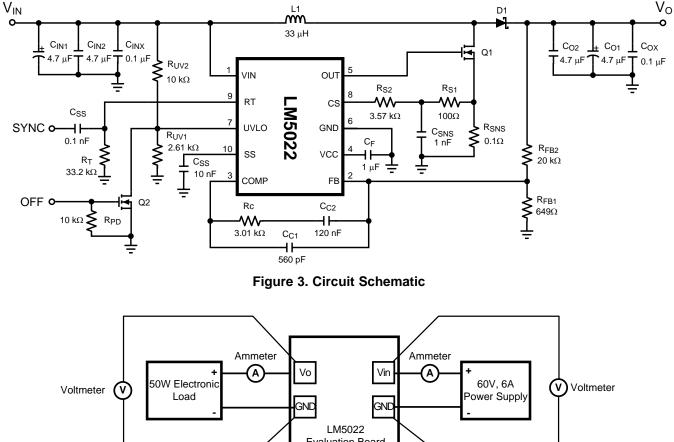
8 **Permanent Components**

The following components should remain the same for any new circuits evaluated on the LM5022 evaluation board:

Name	Value
Cox, Cinx	0.1 µF
Cf	1 µF
Csns	1 nF
Rpd	10 kΩ
Rs1	100Ω

9 **Additional Footprints**

The 100 pF capacitor Csyc provides an AC input path for external clock synchronization. Detection of the sync pulse requires a peak voltage level greater than 3.8V at the RT/SYNC pin. Note that the DC voltage at RT/SYNC is approximately 2V to allow compatibility with 3.3V logic. The sync pulse width should be set between 15 ns to 150 ns by the external components. The Rt resistor is always required, whether the oscillator is free running or externally synchronized. Rt must be selected so that the free-running oscillator frequency is below the lowest synchronization frequency.



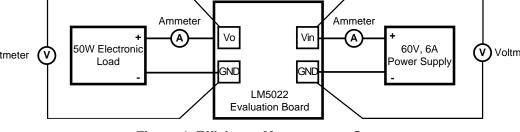


Figure 4. Efficiency Measurement Setup



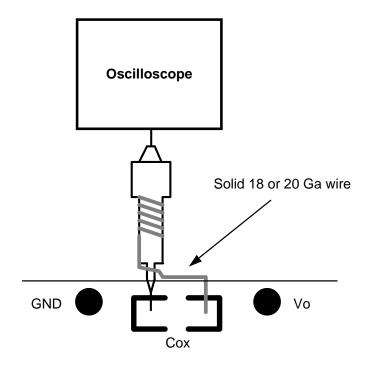


Figure 5. Output Voltage Ripple Measurement Setup



10 Typical Performance Characteristics

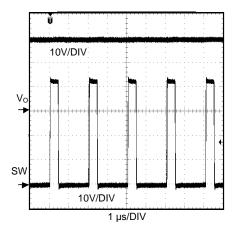


Figure 6. Switch Node Voltage $(V_{IN} = 9V, I_o = 0.5A)$

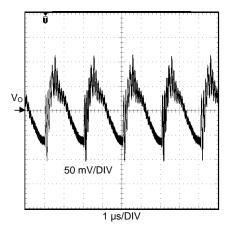


Figure 8. Output Voltage Ripple AC Coupled (V_{IN} = 9V, $I_o = 0.5A$)

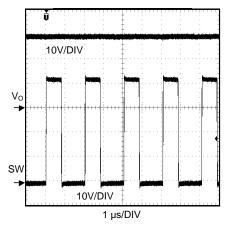


Figure 7. Switch Node Voltage ($V_{IN} = 16V, I_0 = 0.5A$)

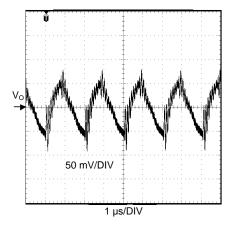
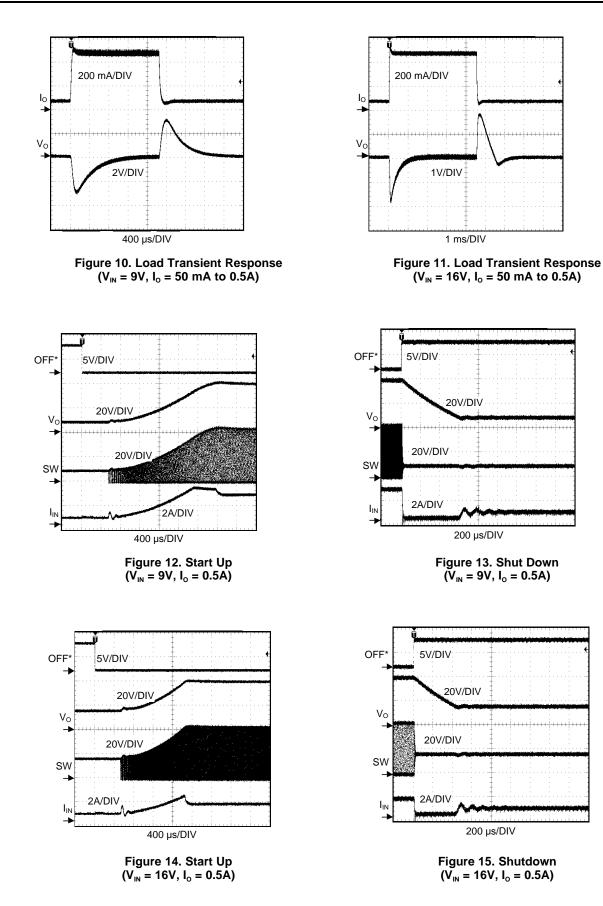


Figure 9. Output Voltage Ripple AC Coupled ($V_{IN} = 16V$, $I_{O} = 0.5A$)







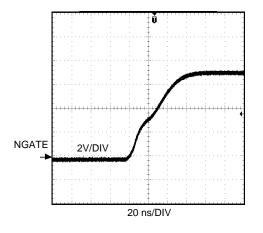


Figure 16. NGATE Rise Time ($V_{IN} = 9V$, $I_0 = 0.1A$, Si4850DY)

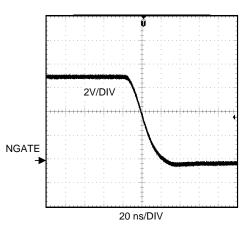


Figure 17. NGATE Fall Time (V_{IN} = 12V, I_0 = 0.1A, Si4850DY)

11 Bill of Materials

ID	Part Number	Туре	Size	Parameters	Qty	Vendor
U1	LM5022	Low-Side Controller	VSSOP-10		1	ТІ
Q1	Si4850EY	MOSFET	SO-8	60V, 31mΩ, 27nC	1	Vishay
D1	CMSH2-60M	Schottky Diode	SMA	60V, 2A	1	Central Semi
L1	SLF12575T-330M3R2	Inductor	12.5x12.5 x7.5mm	33μH, 3.2A, 40mΩ	1	Pulse
Cin1 Cin2	C4532X7R1H475M	Capacitor	1812	4.7µF, 50V	2	TDK
Co1 Co2	C5750X7R2A475M	Capacitor	2220	4.7μF, 100V, 2mΩ	2	TDK
Cf	C3216X7R1E105K	Capacitor	1206	1µF, 25V	1	TDK
Cinx Cox	C2012X7R2A104M	Capacitor	0805	100nF, 100V	2	TDK
Cc1	VJ0805Y561KXXAT	Capacitor	0805	560pF 10%	1	Vishay
Cc2	VJ0805Y124KXXAT	Capacitor	0805	120nF 10%	1	Vishay
Css	VJ0805Y103KXXAT	Capacitor	0805	10nF 10%	1	Vishay
Csns	VJ0805Y102KXXAT	Capacitor	0805	1nF 10%	1	Vishay
Csyc	VJ0805A101KXXAT	Capacitor	0805	100pF 10%	1	Vishay
Rc	CRCW08053011F	Resistor	0805	3.01kΩ 1%	1	Vishay
Rfb1	CRCW08056490F	Resistor	0805	649Ω 1%	1	Vishay
Rfb2	CRCW08052002F	Resistor	0805	20kΩ 1%	1	Vishay
Rs1	CRCW0805101J	Resistor	0805	100Ω 5%	1	Vishay
Rs2	CRCW08053571F	Resistor	0805	3.57kΩ 1%	1	Vishay
Rsns	ERJL14KF10C	Resistor	1210	0.1Ω 1%, 0.5W	1	Vishay
Rt	CRCW08053322F	Resistor	0805	33.2kΩ 1%	1	Vishay
Ruv1	CRCW08052611F	Resistor	0805	2.61kΩ 1%	1	Vishay
Ruv1 Ruv2	CRCW08051002F	Resistor	0805	10kΩ 1%	1	Vishay
VIN, Vo GND GND2	160-1026	Terminal	0.094"		4	Cambion
GND3 GND4 OFF SYNC	160-1512	Terminal	0.062"		4	Cambion



12 PC Board Layout

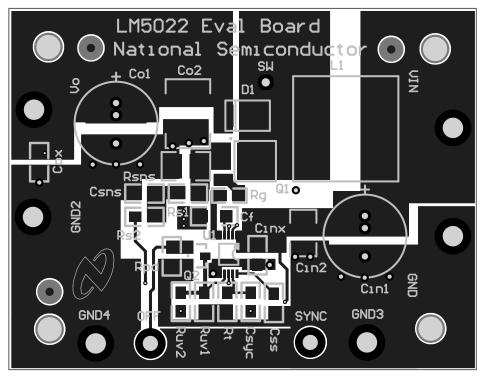


Figure 18. Top Layer and Top Overlay

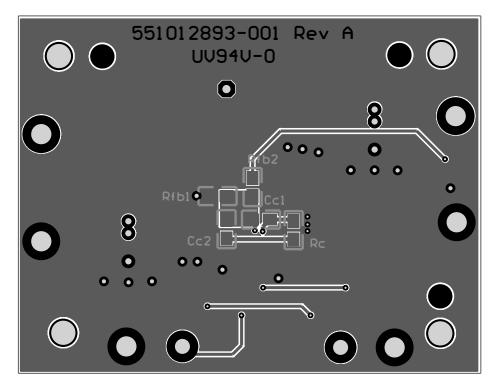


Figure 19. Bottom Layer

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications			
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive		
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications		
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers		
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps		
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy		
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial		
Interface	interface.ti.com	Medical	www.ti.com/medical		
Logic	logic.ti.com	Security	www.ti.com/security		
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense		
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video		
RFID	www.ti-rfid.com				
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com		
Wireless Connectivity	www.ti.com/wirelessconnectivity				

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated